SCONA TPPP 2112 GA

Adhesion promoter for TPE-S overmolding compounds and dispersing agent for nano clays in polypropylene.

Product Data

Composition
Polypropylene functionalized with maleic anhydride

Typical Properties
The values indicated in this data sheet describe typical properties and do not constitute specification limits.

MFR (190 °C, 2.16 kg):	4-8 g/10 min
Drying loss (3 h, 230 °F):	< 0.5 %
MAH content:	0.9-1.2 %
Supplied as:	Granulate

Food Contact Legal Status
For the current food contact legal status, please contact our product safety department or visit www.byk.com for further information.

Storage and Transportation
Storage temperature max. 35 °C / 95 °F, relative humidity < 80 %. Avoid direct sunlight and contact with water.

Special Note
The modifier is also available as a powder under the name SCONA TPPP 2112 FA.

Applications

Thermoplastics

Special Features and Benefits
In TPE-S overmolding compounds, the modifier improves adhesion on hard substrates (such as PC, PA, ABS). Due to the high grafting level, only part of the PP in the TPE compound must be replaced with the modifier. To disperse nano clays, it is recommended that the modifier is used in polypropylene, especially also for solid masterbatches.

Recommended Levels

In overmolding compounds, the amount of additive depends on the PP content of the formulation.
To disperse nano clays, use approx. 100 % of the modifier as supplied based upon the nano clay content.

The above recommended levels can be used for orientation. Optimal levels are determined through a series of laboratory tests.

Incorporation and Processing Instructions

For PP/nano clay compounds, a concentrate made from nano clay and the modifier is created by means of a twin-screw extruder with high shear forces first, which is then incorporated into the PP.

BYK USA Inc.
524 South Cherry Street
P.O. Box 5670
Wallingford, CT 06492
USA
Tel 203 265-2086
Fax 203 284-9158

cs.usa@byk.com
www.byk.com/additives

This issue replaces all previous versions – Printed in the USA